

Product Change Notification - JAON-26BUWR464

Date: 27 Sep 2017
Product Category: Memory
Notification subject: CCB 2729 Final Notice: Qualification of HR-9004 die attach material for selected products available in 8L USON (2x3x0.6mm) package at LPI assembly site.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of HR-9004 die attach material for selected products available in 8L USON (2x3x0.6mm) package at LPI assembly site.

Pre Change:

Using EM-700J die attach material.

Post Change:

Using EM-700J or HR-9004 die attach material

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	LPI assembly site	LPI assembly site	
Wire material	Au wire	Au wire	
Die attach material	EM-700J	EM-700J	HR-9004
Molding compound material	G770HT	G770HT	
Lead frame material	C7025	C7025	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying HR-9004 die attach material.

Change Implementation Status:

In Progress

Estimated First Ship Date:

October 27, 2017 (date code: 1743)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2017					October 2017			
Workweek	35	36	37	38	39	40	41	42	43
Qual Report Availability					X				
Final PCN Issue Date					X				
Estimated Implementation Date									X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

September 27, 2017: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-26BUWR464_Qual_Report.pdf](#)
- [PCN_JAON-26BUWR464_Affected_CPN.pdf](#)
- [PCN_JAON-26BUWR464_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-26BUWR464
CATALOG_PART_NBR
SST25PF020B-80-4C-Q3AE-T
SST25VF020B-80-4C-Q3AE-T
SST25VF020B-80-4I-Q3AE-100-T
SST25VF020B-80-4I-Q3AE-HCT-T
SST25VF020B-80-4I-Q3AE-T
SST25WF020AT-40I/NP
SST25WF040BT-40I/NP
SST25WF040BT-40I/NP-100
SST25WF080BT-40I/NP
SST26WF040BAT-104I/NP
SST26WF040BT-104I/NP
SST26WF080BAT-104I/NP
SST26WF080BT-104I/NP